

EAST - [default1.wsp:1]

File View Edit Tools Window Help

Drafts

Pending

Active

- L1: (1) ("6393374").PN.
- L2: (1937) junction adj temperature
- L3: (4671) power adj management
- L4: (16) 2 and 3
- L5: (2097) thermal adj management
- L6: (95) 2 and 5
- L7: (1) bios and 6
- L8: (1) "6182238".PN.
- L9: (1) "6173217".PN.
- L10: (1) "6105142".PN.
- L11: (1) "5838987".PN.
- L12: (1) "5760636".PN.
- L13: (1) "6507530".PN.**

Failed

Saved

Favorites

Tagged (0)

UDC

Queue

Trash

U	I	Document ID	Issue Date	Pages	Title
<input type="checkbox"/>	<input type="checkbox"/>	US 6507530 B1	20030114	7	Weighted throttling mechanism with rank based throttling for a memory system

IEEE HOME | SEARCH IEEE | SHOP | WEB ACCOUNT | CONTACT IEEE



Membership | Publications/Services | Standards | Conferences | Careers/Jobs

IEEE Xplore®
 RELEASE 1.6

 Welcome
 United States Patent and Trademark Office

IEEE Xplore®
 1 Million Documents
 1 Million Users
 And Growing
 » Search Results

[Help](#) [FAQ](#) [Terms](#) [IEEE Peer Review](#)
[Quick Links](#)

Welcome to IEEE Xplore®

- ☐ Home
- ☐ What Can I Access?
- ☐ Log-out

Tables of Contents

- ☐ Journals & Magazines
- ☐ Conference Proceedings
- ☐ Standards

Search

- ☐ By Author
- ☐ Basic
- ☐ Advanced

Member Services

- ☐ Join IEEE
- ☐ Establish IEEE Web Account
- ☐ Access the IEEE Member Digital Library

Your search matched **10** of **569** documents.A maximum of **500** results are displayed, **15** to a page, sorted by **Relevance** in **Descending** order.**Refine This Search:**

You may refine your search by editing the current search expression or entering a new one in the text box.

(((thermal management) and (pyr >= 1951 and pyr <= 1

Search

☐ Check to search within this result set**Results Key:****JNL** = Journal or Magazine **CNF** = Conference **STD** = Standard
1 Development of a thermal management solution for a ruggedized Pentium based notebook computer
Rujano, J.R.; Cardenas, R.; Rahman, M.M.; Moreno, W.A.;

Thermal and Thermomechanical Phenomena in Electronic Systems, 1998. ITherm '98. The Sixth Intersociety Conference on , 27-30 May 1998

Pages:8 - 14

[\[Abstract\]](#) [\[PDF Full-Text \(820 KB\)\]](#) **IEEE CNF**
2 Robust/low cost SSPCs are finally available
Friedman, S.;

Digital Avionics Systems Conference, 1997. 16th DASC., AIAA/IEEE , Volume: 2 , 26-30 Oct. 1997

Pages:7.3 - 31-7.3-36 vol.2

[\[Abstract\]](#) [\[PDF Full-Text \(468 KB\)\]](#) **IEEE CNF**
3 Comparison of electrical performance of enhanced BGA's
Kaw, R.; Hanna, B.; Devnani, N.;

Components, Packaging, and Manufacturing Technology, Part B: Advanced Packaging, IEEE Transactions on [see also Components, Hybrids, and Manufacturing Technology, IEEE Transactions on] , Volume: 21 , Issue: 2 , May 1998

Pages:164 - 170

[\[Abstract\]](#) [\[PDF Full-Text \(244 KB\)\]](#) **IEEE JNL**
4 Exceptional performance from the development, qualification and implementation of a silicone adhesive for bonding heatsinks to semiconductor packages

Bosworth, S.; Hsu, S.C.; Polcari, J.;

Components, Packaging, and Manufacturing Technology, Part A, IEEE Transactions on [see also Components, Hybrids, and Manufacturing Technology, IEEE Transactions on] , Volume: 18 , Issue: 1 , March 1995
Pages:94 - 100

[[Abstract](#)] [[PDF Full-Text \(624 KB\)](#)] IEEE JNL

5 Robust/low cost solid-state remote power controller (RPC) technology is here

Friedman, S.N.;

Digital Avionics Systems Conference, 1999. Proceedings. 18th , Volume: 1/17 pp. vol.1 , 24-29 Oct. 1999

Pages:3.B.4-1 - 3.B.4-7 vol.1

[[Abstract](#)] [[PDF Full-Text \(492 KB\)](#)] IEEE CNF

6 The use of heat pipes in personal computers

Xie, H.; Ali, A.; Bhatia, R.;

Thermal and Thermomechanical Phenomena in Electronic Systems, 1998. ITherm '98. The Sixth Intersociety Conference on , 27-30 May 1998

Pages:442 - 448

[[Abstract](#)] [[PDF Full-Text \(712 KB\)](#)] IEEE CNF

7 Thermal design of a ultra-slim notebook computer

Kobayashi, T.; Ogushi, T.; Sumi, N.; Fujii, M.;

Thermal and Thermomechanical Phenomena in Electronic Systems, 1998. ITherm '98. The Sixth Intersociety Conference on , 27-30 May 1998

Pages:15 - 21

[[Abstract](#)] [[PDF Full-Text \(664 KB\)](#)] IEEE CNF

8 Ball-grid-array package thermal management

Chung, K.;

Semiconductor Thermal Measurement and Management Symposium, 1998. SEMI-THERM Proceedings 1998., Fourteenth Annual IEEE , 10-12 March 1998

Pages:78 - 87

[[Abstract](#)] [[PDF Full-Text \(1020 KB\)](#)] IEEE CNF

9 Comparison of electrical performance of enhanced BGAs

Kaw, R.; Hanna, B.; Devnani, N.;

Electronic Components and Technology Conference, 1997. Proceedings., 47th , 18-21 May 1997

Pages:682 - 688

[[Abstract](#)] [[PDF Full-Text \(604 KB\)](#)] IEEE CNF

10 The use of heat pipes in the cooling of portables with high power packages-A case study with the Pentium processor-based notebooks and sub-notebooks

Xie, H.; Aghazadeh, M.; Toth, J.;

Electronic Components and Technology Conference, 1995. Proceedings., 45th , 21-24 May 1995
Pages:906 - 913

[\[Abstract\]](#) [\[PDF Full-Text \(764 KB\)\]](#) **IEEE CNF**

[Home](#) | [Log-out](#) | [Journals](#) | [Conference Proceedings](#) | [Standards](#) | [Search by Author](#) | [Basic Search](#) | [Advanced Search](#) | [Join IEEE](#) | [Web Account](#) | [New this week](#) | [OPAC Linking Information](#) | [Your Feedback](#) | [Technical Support](#) | [Email Alerting](#) | [No Robots Please](#) | [Release Notes](#) | [IEEE Online Publications](#) | [Help](#) | [FAQ](#) | [Terms](#) | [Back to Top](#)

Copyright © 2004 IEEE — All rights reserved